



SOT-23-3 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition		CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English			
Die	0.5	Si		7440-21-3	100.00%
Lead Frame	3.263	Cu		7440-50-8	balance
		Fe		7439-89-6	2.1-2.6%
		P		7723-14-0	0.015-0.15%
		Zn		7440-66-6	0.05-0.20%
		Pb		7439-92-1	≤0.005%
Epoxy	0.05	Silver		7440-22-4	70- < 90 %
		Epoxy Resin.		9003-36-5	10- < 20 %
		butane		2425-79-8	3- < 10 %
		dapsone		80-08-0	1- < 2.5 %
Wire	0.045	Cu		7440-50-8	99.99%
		Others		—	0.01%
Mold Compound	9.745	Epoxy Resin A		—	1-5%
		Epoxy Resin B		—	1-5%
		Phenol Resin		—	5~10%
		Silica(Amorphous) A		60676-86-0	70-90%
		Silica(Amorphous)B		7631-86-9	5-10%
		Carbon Black		1333-86-4	0.1-1%
Plating	0.12	Sn		7440-31-5	99.990%
Total	13.723				

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.